

11. The electronic assembly as claimed in claim **10**, wherein the transparent conductive layer comprises indium tin oxide.

12. The electronic assembly as claimed in claim **8**, wherein the device substrate further comprises:

an array of plugs, disposed in and insulated from the device substrate and electrically connected to the array of optoelectronic devices;

a ball grid array, correspondingly disposed on the array of plugs; and

at least one grounding ball, correspondingly disposed on the grounding pad.

13. The electronic assembly as claimed in claim **8**, wherein the conductive layer comprises metal.

14. An electronic assembly for an image sensor device, comprising:

a package module, comprising,

a device substrate, comprising an array of optoelectronic devices therein,

a transparent substrate, comprising a dam portion attached to the device substrate to form a cavity between the device and transparent substrates, and a micro-lens array disposed on the device substrate and within the cavity;

a lens set mounted on the package module; and

a permeability layer covering the sidewalls of the lens set and the package module and the upper surface of the lens set, having an opening allowing light to reach the array of optoelectronic devices.

15. The electronic assembly as claimed in claim **14**, further comprising an opaque layer covering the permeability layer.

16. The electronic assembly as claimed in claim **14**, wherein the device substrate further comprises:

an array of plugs, disposed in and insulated from the device substrate and electrically connected to the array of optoelectronic devices; and

a ball grid array, correspondingly disposed on the array of plugs.

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